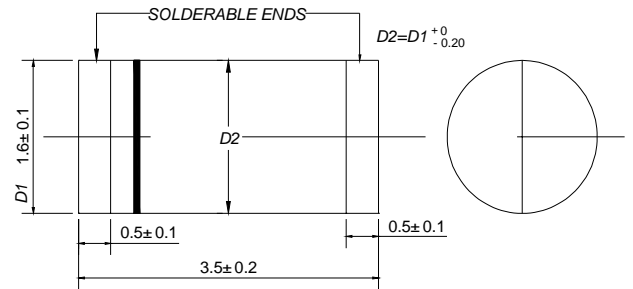




Features

- Plastic package has underwriters laboratories flammability classification 94V-0
- Glass passivated chip junction
- For surface mount applications
- High temperature metallurgically bonded construction
- Cavity-free glass passivated junction
- High temperature soldering guaranteed:450 /5 seconds at terminals.Complete device sub-mersible temperature of 265 for 10 seconds in solder bath

DO - 213AA



Dimensions in millimeters

Mechanical Data

- Case: JEDEC DO-213AA,molded plastic
- Polarity: Color band denotes cathode
- Weight: 0.0014 ounces, 0.036 grams
- Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 ambient temperature unless otherwise specified.

Single phase,half wave,60 Hz,resistive or inductive load. For capacitive load,derate current by 20%.

		EGL 341A	EGL 341B	EGL 341D	EGL 341F	EGL 341G	EGL 341H	EGL 341J	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	300	400	500	600	V
Maximum RMS voltage	V_{RMS}	35	70	140	210	280	350	420	V
Maximum DC blocking voltage	V_{DC}	50	100	200	300	400	500	600	V
Maximum average forward rectified current $T_T=75$	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Maximum instantaneous forward voltage @1.0A	V_F	1.25		1.35		1.70		V	
Maximum reverse current @ $T_A=25$ at rated DC blocking voltage @ $T_A=125$	I_R	5.0							μA
Maximum reverse recovery time (Note 1)	t_{rr}	50							ns
Typical junction capacitance (Note 2)	C_j	15							pF
Typical thermal resistance (Note 3)	R_{0JA}	150							K/W
Operating junction temperature range	T_j	- 55 ---- +175							
Storage temperature range	T_{STG}	- 55 ---- +175							

NOTE: 1. Measured with $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$

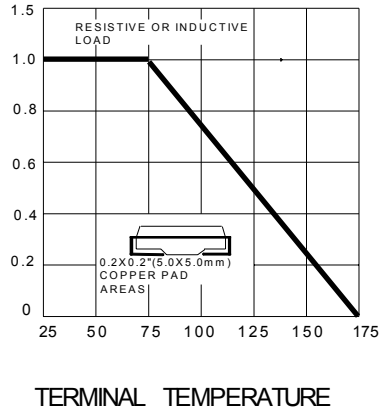
2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3. Thermal resistance from junction to ambient, 0.24×0.24"(6.0×6.0mm) copper pads to each terminal.

Ratings AND Characteristic Curves

FIG.1 – FORWARD CURRENT DERATING CURV

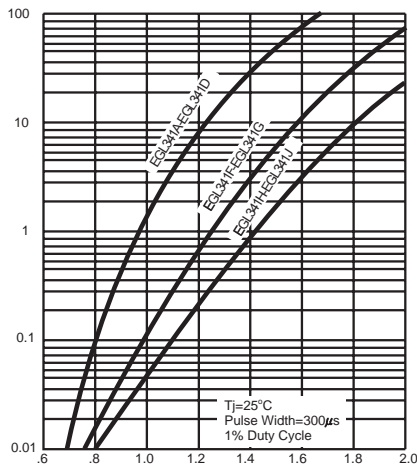
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES



TERMINAL TEMPERATURE

FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

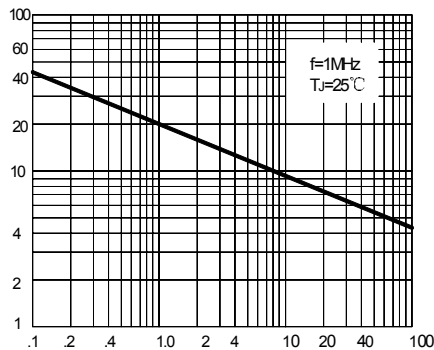
INSTANTANEOUS FORWARD CURRENT, AMPERES



INSTANTANEOUS FORWARD VOLTAGE(V)

FIG.5 – TYPICAL JUNCTION CAPACITANCE

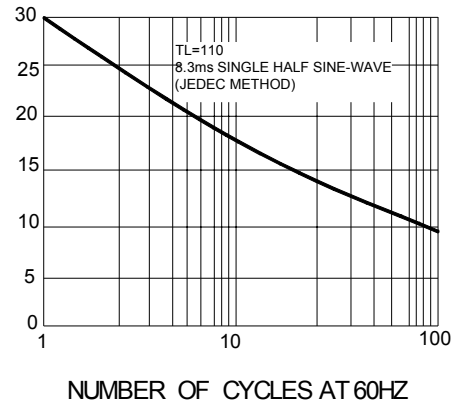
JUNCTION CAPACITANCE(pF)



REVERSE VOLTAGE(V)

FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

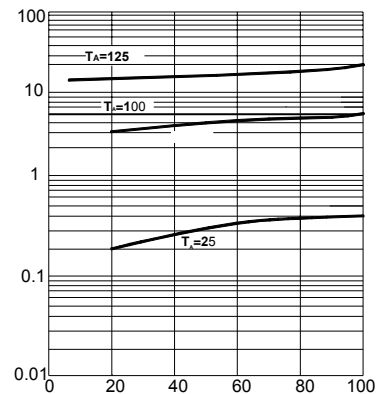
PEAK FORWARD SURGE CURRENT, AMPERES



NUMBER OF CYCLES AT 60HZ

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

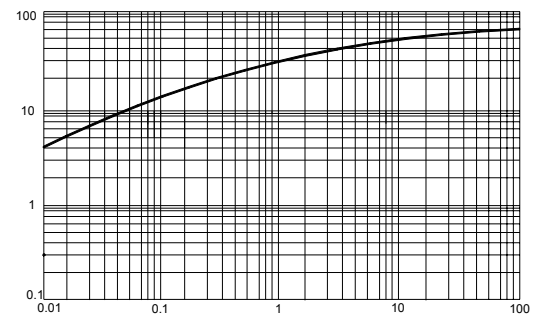
INSTANTANEOUS REVERSE LEAKAGE CURRENT (mA)



PERCENT OF RATED PEAK REVERSE VOLTAGE. (%)

FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE

TRANSIENT THERMAL IMPEDANCE (°C/W)



T,PULSE DURATION,